

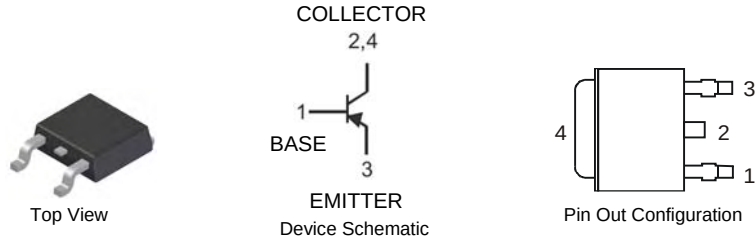
HIGH VOLTAGE PNP SURFACE MOUNT TRANSISTOR

Features

- Epitaxial Planar Die Construction
- High Collector-Emitter Voltage
- Ideally Suited for Automated Assembly Processes
- Ideal for Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

Mechanical Data

- Case: DPAK
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish — Matte Tin annealed over Copper Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.34 grams (approximate)



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-300	V
Collector-Emitter Voltage	V _{CEO}	-300	V
Emitter-Base Voltage	V _{EBO}	-3	V
Continuous Collector Current	I _C	-0.5	A
Peak Pulse Collector Current	I _{CM}	-0.75	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @T _C = 25°C	P _D	15	W
Thermal Resistance, Junction to Case	R _{θJC}	8.33	°C/W
Power Dissipation @T _A = 25°C (Note 3)	P _D	1.56	W
Thermal Resistance, Junction to Ambient	R _{θJA}	81	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Emitter Sustaining Voltage (Note 4)	V _{(SUS)CEO}	-300	—	—	V	I _C = -1mA, I _B = 0
Collector Cutoff Current	I _{CBO}	—	—	-100	μA	V _{CB} = -300V, I _E = 0
Emitter Cutoff Current	I _{EBO}	—	—	-100	μA	V _{EB} = -3V, I _C = 0
ON CHARACTERISTICS (Note 4)						
DC Current Gain	h _{FE}	30	—	240	—	V _{CE} = -10V, I _C = -50mA

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB with the minimum pad size recommended.
 4. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%.

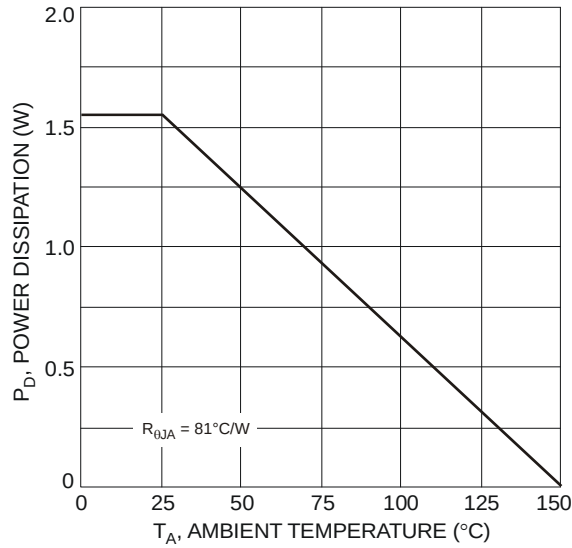


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

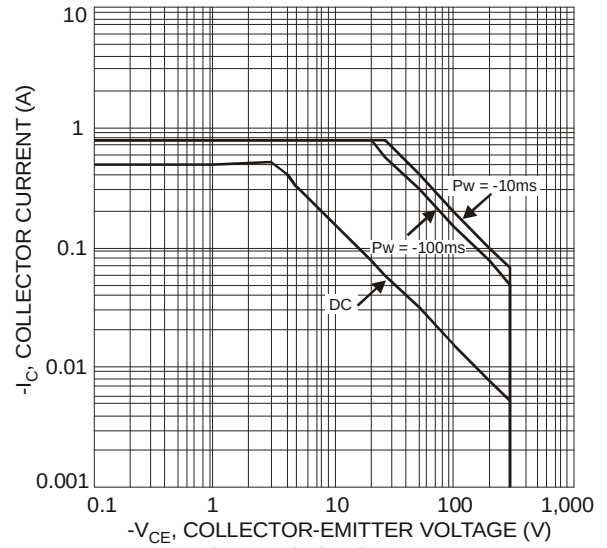


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage (Note 3)

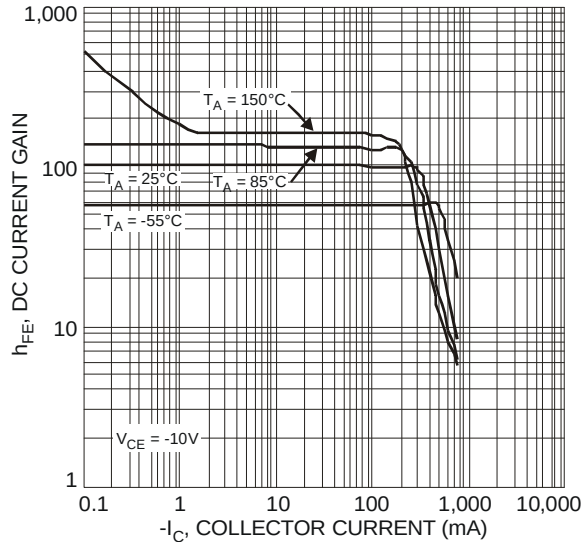


Fig. 3 Typical DC Current Gain vs. Collector Current

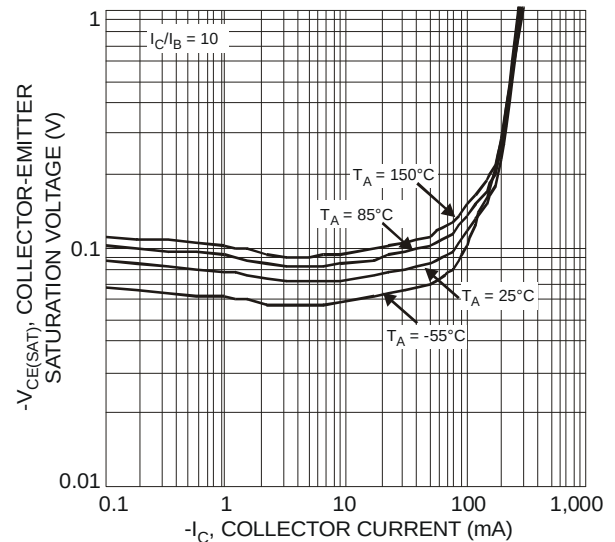


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

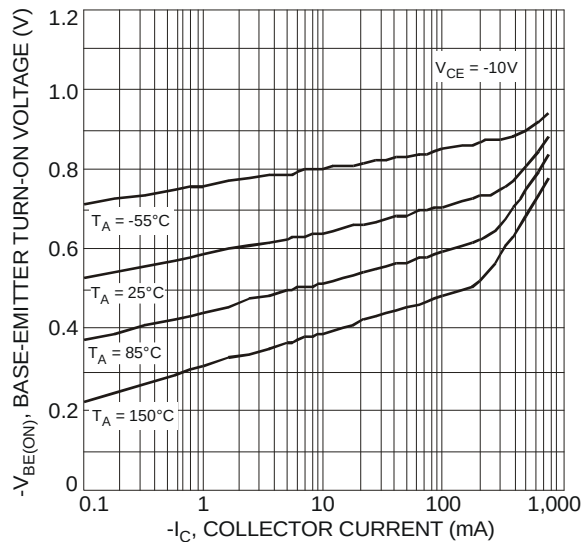


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

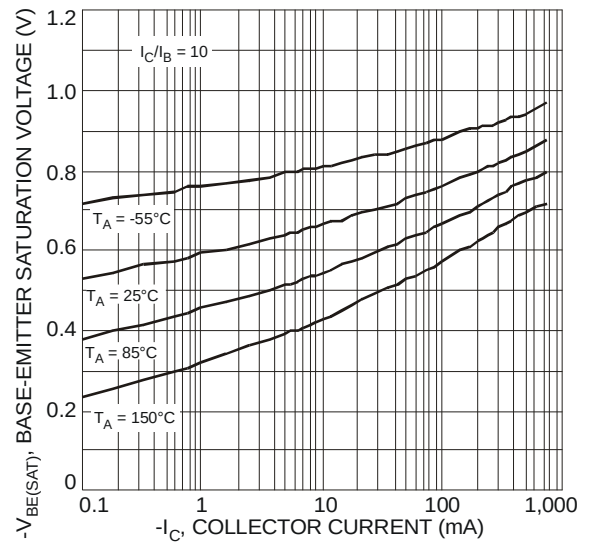


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

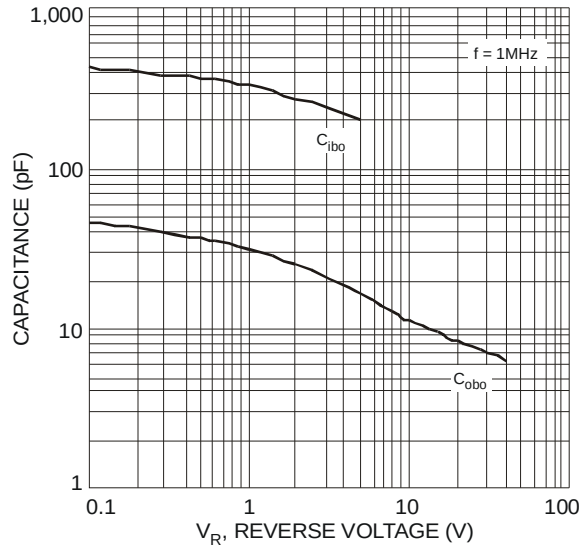


Fig. 7 Typical Capacitance Characteristics

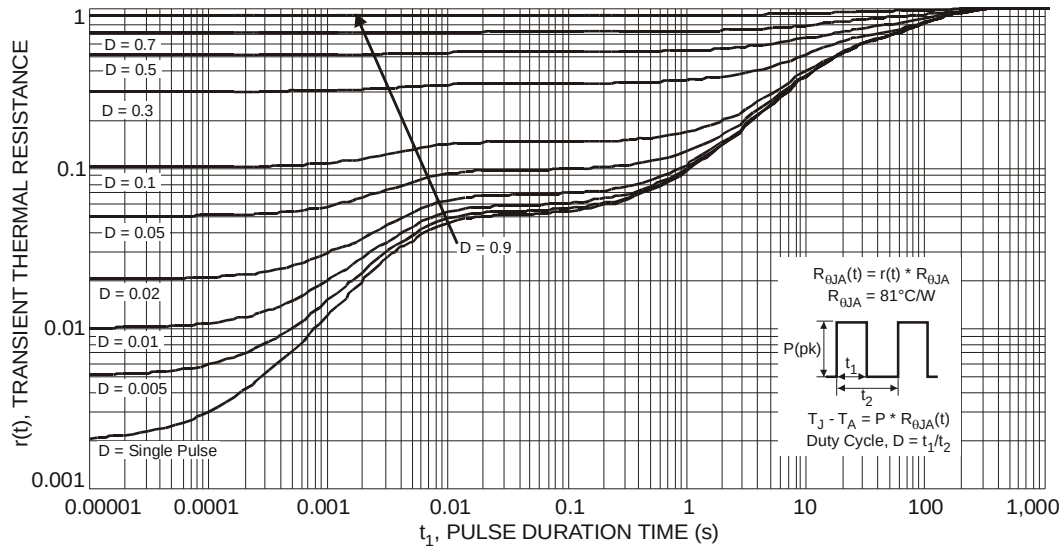


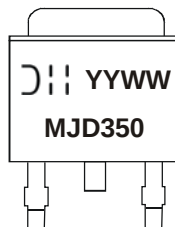
Fig. 8 Transient Thermal Response (Note 3)

Ordering Information (Note 5)

Part Number	Case	Packaging
MJD350-13	DPAK	2500/Tape & Reel

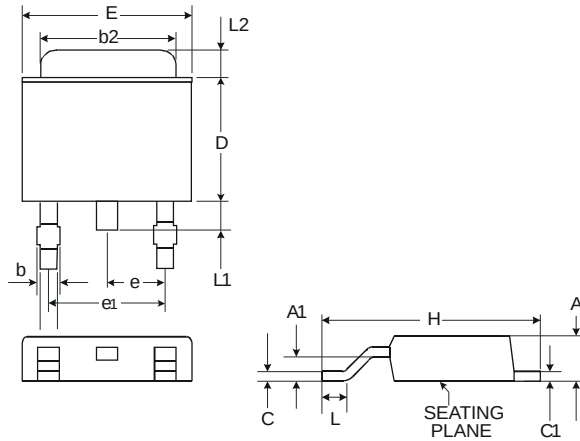
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



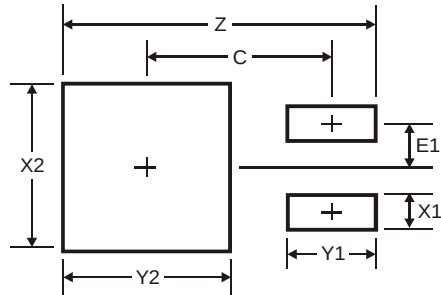
MJD350 = Product Type Marking Code
DII = Manufacturers' code marking
YYWW = Date Code Marking
YY = Last Digit of Year, (ex: 08 = 2008)
WW = Week Code 01-52

Package Outline Dimensions



DPAK		
Dim	Min	Max
A	2.18	2.40
A1	0.89	1.14
b	0.61 Typ	
b2	5.20	5.50
C	0.45	0.58
C1	0.45	0.58
D	5.40	6.20
E	6.35	6.80
e	2.28 Typ	
e1	4.57 Typ	
H	9.00	10.40
L	0.51	—
L1	0.64	1.02
L2	0.88	1.27
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
C	6.9
E1	2.3

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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